

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT4698367

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
TAEKYUNG YOO	11/17/2017
DAEWON KIM	11/16/2017
SEONGBOK YOON	11/16/2017
YELIM WON	11/09/2017
MYUNGJI MOON	11/09/2017
HANBEET CHANG	11/09/2017
YONGPIL KIM	11/09/2017
JAESOO PARK	11/09/2017
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	LUMENS CO., LTD.
<b>Street Address:</b>	12 WONGOMAE-RO, GIHEUNG-GU
<b>City:</b>	YONGIN-SI, GYEONGGI-DO
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>Postal Code:</b>	17086
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	15818738
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Email:</b>	kmun@meimark.com
<b>Correspondent Name:</b>	MEI & MARK LLP
<b>Address Line 1:</b>	P.O. BOX 65981
<b>Address Line 4:</b>	WASHINGTON, D.C. 20035-5981
<b>ATTORNEY DOCKET NUMBER:</b>	83001.0040-00
<b>NAME OF SUBMITTER:</b>	K. KEVIN MUN
<b>SIGNATURE:</b>	/K. Kevin Mun/
<b>DATE SIGNED:</b>	11/21/2017

**Total Attachments: 4**

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ASSIGNMENT

WHEREAS, We, the below named inventors (hereinafter referred to as "Assignors"), have made an invention entitled:

**MICRO-LED MODULE AND METHOD FOR FABRICATING THE SAME**

for which we executed an application for United States Letters Patent

- ☒ concurrently herewith, or
- ☐ filed as Application No. \_\_\_\_\_ on \_\_\_\_\_, and

WHEREAS, **LUMENS CO., LTD.** (hereinafter referred to as "Assignee"), organized and operating under the laws of the Republic of Korea, whose post office address is **12 Wongomae-ro, Giheung-gu, Yongin-si, Gyeonggi-do, 17086, Republic of Korea**, is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issues upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, Assignors have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto Assignee, its lawful successors and assigns, the entire right, title, and interest in and to this invention, this application, all divisions and continuations thereof, all Letters Patent of the United States which may be granted thereon, all reissues thereof, all rights to claim priority on the basis of this application, all applications for Letters Patent which may hereafter be filed for this invention in any foreign country, all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and Assignors hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, ASSIGNORS HEREBY covenant that Assignors have the full right to convey the interest assigned by this Assignment, and Assignors have not executed and will not execute any agreement in conflict with this Assignment;

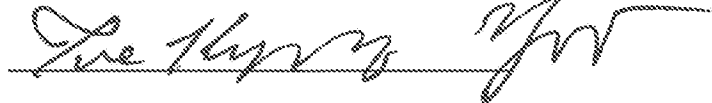
AND, ASSIGNORS HEREBY further covenant and agree, without further consideration, that Assignors will communicate with Assignee, its successors and assigns, any facts known to Assignors respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid

Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

\* \* \*

IN TESTIMONY WHEREOF, We have executed this Assignment.

Signature of Inventor:



Inventor Name:

Taekyung YOO

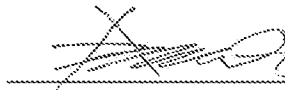
Citizenship:

Republic of Korea

Date:

Nov. 17, 2017

Signature of Inventor:



Inventor Name:

Daewon KIM

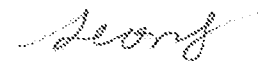
Citizenship:

Republic of Korea

Date:

Nov 16, 2017

Signature of Inventor:



Inventor Name:

Seongbok YOON

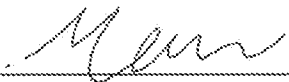
Citizenship:

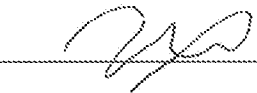
Republic of Korea

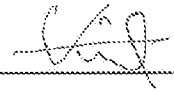
Date:

Nov 16, 2017


Signature of Inventor:   
Inventor Name: Yelim WON  
Citizenship: Republic of Korea  
Date: Nov. 9 2017

Signature of Inventor:   
Inventor Name: Myungji MOON  
Citizenship: Republic of Korea  
Date: 2017. 11. 9

Signature of Inventor:   
Inventor Name: Hanbeet CHANG  
Citizenship: Republic of Korea  
Date: 2017. 11. 09

Signature of Inventor:   
Inventor Name: Yongpil KIM  
Citizenship: Republic of Korea  
Date: Nov 11. 9

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Signature of Inventor:   
Inventor Name: Jaesoon PARK  
Citizenship: Republic of Korea  
Date: Nov. 04, 2017